original

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Atty. Docket

PHA 23,843

AVEED MAJID ET AL

ial No. $09\440,595$

Group Art Unit: 2811

November 15, 1999

Examiner: N. Parekh

Title:

MULTIPLE SEMICONDUCTOR CHIP (MULTI-CHIP) MODULE FOR USE IN

POWER APPLICATIONS

Commissioner for Patents Washington, D.C.

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

This amendment is in response to the Final Official Action dated July 24, 2001, in which all of the currently-pending claim were finally rejected. In order to place this application an condition for allowance or in better form for consideration on appeal (Notice of Appeal filed herewith), it is respectfull requested that this amendment be entered and that the claims be amended as follows:

IN THE CLAIMS

Kindly amend claims 1 as follows:

(twice amended) A multiple semiconductor chip (multi-chip) module, comprising at least a power semiconductor chip and a